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October 2013

FDME430NT

Features

- Max $r_{DS(on)}$ = 40 m Ω at V_{GS} = 4.5 V, I_D = 6 A
- Max $r_{DS(on)}$ = 51 m Ω at V_{GS} = 2.5 V, I_D = 5 A
- Max $r_{DS(on)}$ = 71 m Ω at V_{GS} = 1.8 V, I_D = 4 A
- Low profile: 0.55 mm maximum in the new package MicroFET 1.6x1.6 **Thin**
- Free from halogenated compounds and antimony oxides
- RoHS Compliant

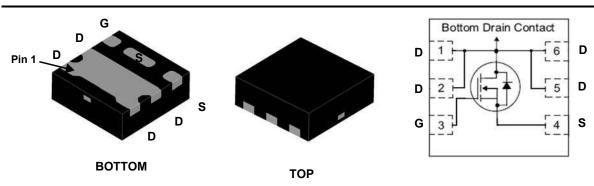
General Description

This single N-Channel MOSFET has been designed using Fairchild Semiconductor's advanced PowerTrench® process to optimize the $r_{DS(ON)} \ @\ V_{GS}$ = 1.8 V on special MicroFET leadframe.

Applications

- Li-lon Battery Pack
- Baseband Switch
- Load Switch
- DC-DC Conversion





MicroFET 1.6x1.6 Thin

MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Paramet	Parameter				
V_{DS}	Drain to Source Voltage			30	V	
V_{GS}	Gate to Source Voltage			±12	V	
	Drain Current -Continuous	T _A = 25 °C	(Note 1a)	6	A	
ID	-Pulsed			30	7 ^	
В	Power Dissipation for Single Operation	T _A = 25 °C	(Note 1a)	2.1	w	
P _D	Power Dissipation for Single Operation	T _A = 25 °C	(Note 1b)	0.7	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
T _J , T _{STG}	Operating and Storage Junction Temperature Range			-55 to +150	°C	

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	60	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	175	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
YA	FDME430NT	MicroFET 1.6x1.6 Thin	7 "	8 mm	5000 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	I _D = 250 μA, V _{GS} = 0 V	30			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C		22		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 24 V, V _{GS} = 0 V			1	μΑ
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	0.6	8.0	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = 250 μA, referenced to 25 °C		-3		mV/°C
		$V_{GS} = 4.5 \text{ V}, I_D = 6 \text{ A}$		25	40	
_	Drain to Source On Desigtance	$V_{GS} = 2.5 \text{ V}, I_D = 5 \text{ A}$		29	51	mΩ
DS(on)	r _{DS(on)} Drain to Source On Resistance	$V_{GS} = 1.8 \text{ V}, I_D = 4 \text{ A}$		38	71	1117.5
	$V_{GS} = 4.5 \text{ V}, I_D = 6 \text{ A}, T_J = 125 ^{\circ}\text{C}$		34	54		
g _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 6 \text{ A}$		31		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V - 45 V V - 0 V	572	760	pF
Coss	Output Capacitance	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz	74	100	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 WH 12	51	75	pF

Switching Characteristics

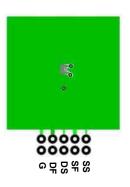
t _{d(on)}	Turn-On Delay Time		7	14	ns
t _r	Rise Time	V_{DD} = 15 V, I_{D} = 6 A, V_{GS} = 4.5 V, R_{GEN} = 6 Ω	3	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 4.5 V, R _{GEN} = 6 Ω	19	34	ns
t _f	Fall Time		3.3	10	ns
Q_{g}	Total Gate Charge	V 45.V L 0.A	6.5	9	nC
Q _{gs}	Gate to Source Gate Charge	$V_{DD} = 15 \text{ V}, I_{D} = 6 \text{ A},$ $V_{GS} = 4.5 \text{ V}$	0.9		nC
Q_{gd}	Gate to Drain "Miller" Charge	VGS = 4.0 V	1.6		nC

Drain-Source Diode Characteristics

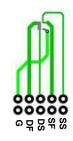
V Source to	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = 6 A	(Note 2)	8.0	1.2	V
v _{SD}	V _{SD} Source to Drain blode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 1.6 \text{ A}$	(Note 2)	0.7	1.2	V
t _{rr}	Reverse Recovery Time	I _F = 6 A, di/dt = 100 A/μs		12	22	ns
Q _{rr}	Reverse Recovery Charge			2.9	10	nC

Notes

^{1.} R_{0,JA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



a. 60 °C/W when mounted on a 1 in² pad of 2 oz copper.



b. 175 °C/W when mounted on a minimum pad of 2 oz copper.

^{2.} Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0%.

Typical Characteristics T_J = 25 °C unless otherwise noted

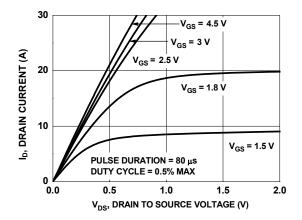


Figure 1. On Region Characteristics

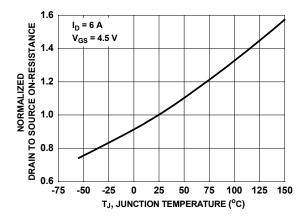


Figure 3. Normalized On Resistance vs Junction Temperature

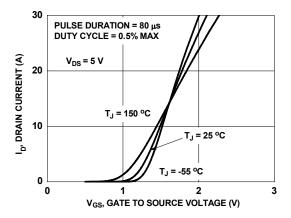


Figure 5. Transfer Characteristics

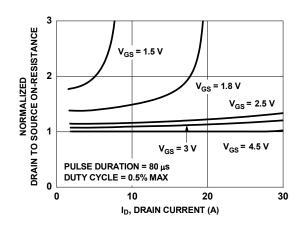


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

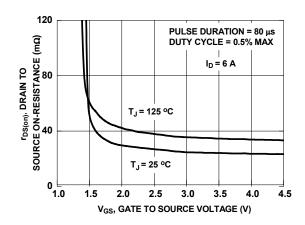


Figure 4. On-Resistance vs Gate to Source Voltage

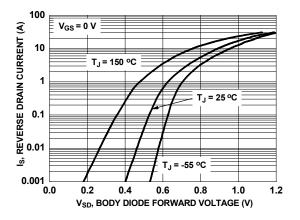


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25 \, ^{\circ}\text{C}$ unless otherwise noted

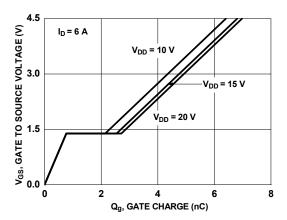


Figure 7. Gate Charge Characteristics

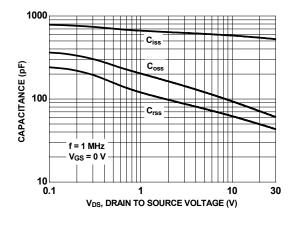


Figure 8. Capacitance vs Drain to Source Voltage

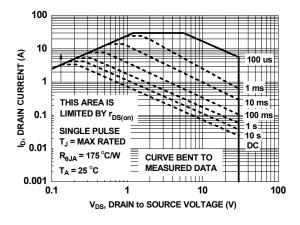


Figure 9. Forward Bias Safe Operating Area

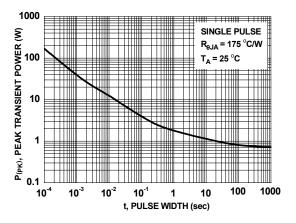


Figure 10. Single Pulse Maximum Power Dissipation

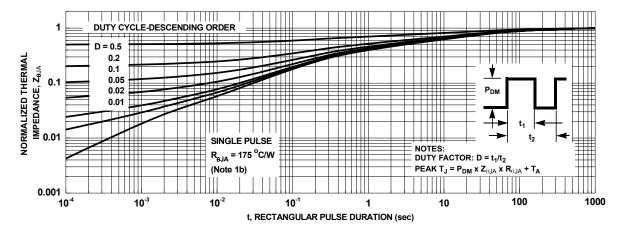
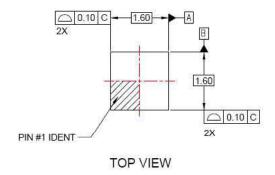
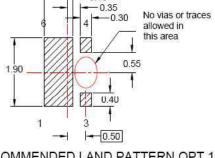


Figure 11. Junction-to-Ambient Transient Thermal Response Curve

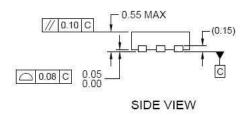
Dimensional Outline and Pad Layout

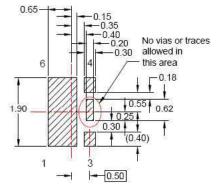


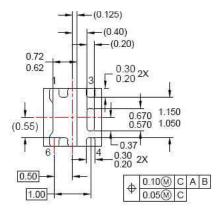


RECOMMENDED LAND PATTERN OPT 1

0.65







RECOMMENDED LAND PATTERN OPT 2

NOTES:

- A. DOES NOT FULLY CONFORM TO JEDEC REGISTRATION
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- D. LAND PATTERN RECOMMENDATION IS BASED ON FSC DESIGN ONLY





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